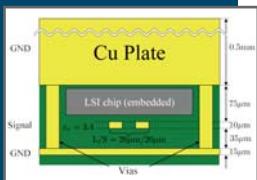
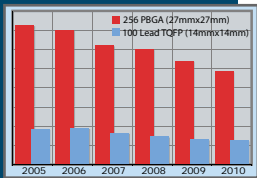
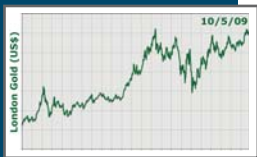
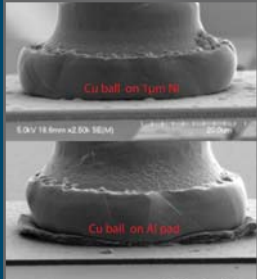


Advanced Packaging Update: Market and Technology Trends

Vol. 2, 2009



The second volume of the Advanced Packaging Update for 2009 provides an updated economic outlook for the world economy and the semiconductor packaging and assembly sector. This issue features TechSearch International's annual survey on IC package assembly price trends. Packages include QFPs, PBGAs, flip chip PBGAs, leadframe CSPs (QFNs, etc.), and laminate CSPs (FBGA). An analysis of the trends in the movement to copper wire bonding as a cost-savings strategy is also provided. Special coverage of substrate design rules from suppliers of organic flip chip substrates, PBGAs, and laminate CSPs worldwide is highlighted. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com

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